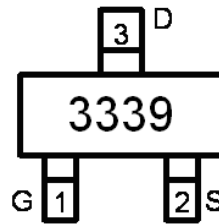
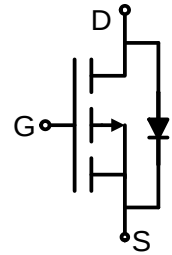


Main Product Characteristics:

V_{DS}	-30V
$R_{DS(on)}$	37m Ω (typ.)
I_D	-4.1A ①


SOT-23

**Marking and pin
Assignment**

Schematic diagram
Features and Benefits:

- Advanced MOSFET process technology
- Special designed for PWM, load switching and general purpose applications
- Ultra low on-resistance with low gate charge
- Fast switching and reverse body recovery
- 150°C operating temperature


Description:

It utilizes the latest processing techniques to achieve the high cell density and reduces the on-resistance with high repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in power switching application and a wide variety of other applications.

Absolute max Rating: @T_A=25°C unless otherwise specified

Symbol	Parameter	Max.	Units
I_D @ TC = 25°C	Continuous Drain Current, V_{GS} @ 10V	-4.1 ①	A
I_D @ TC = 70°C	Continuous Drain Current, V_{GS} @ 10V	-3.5 ①	
I_{DM}	Pulsed Drain Current ②	-20	
P_D @TC = 25°C	Power Dissipation ③	1.4	W
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-to-Source Voltage	± 20	V
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	°C

Thermal Resistance

Symbol	Characterizes	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-ambient (t ≤ 10s) ④	—	90	°C /W

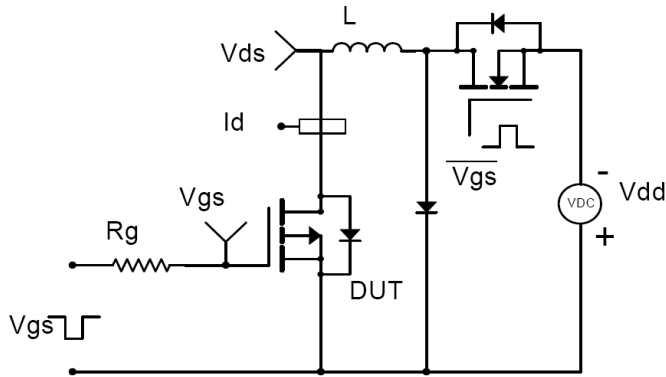
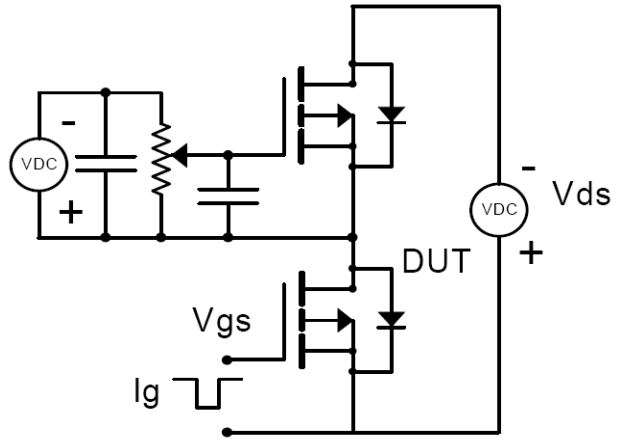
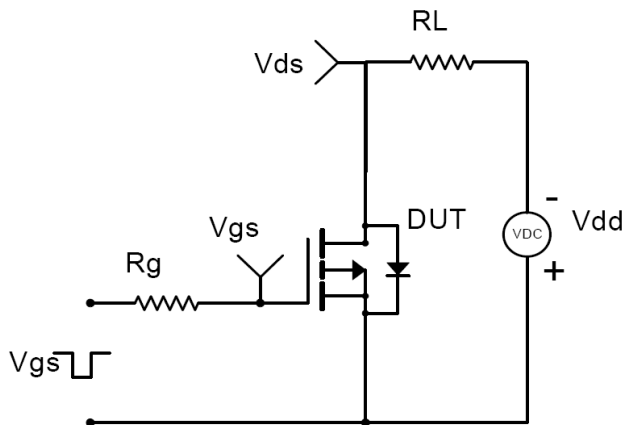
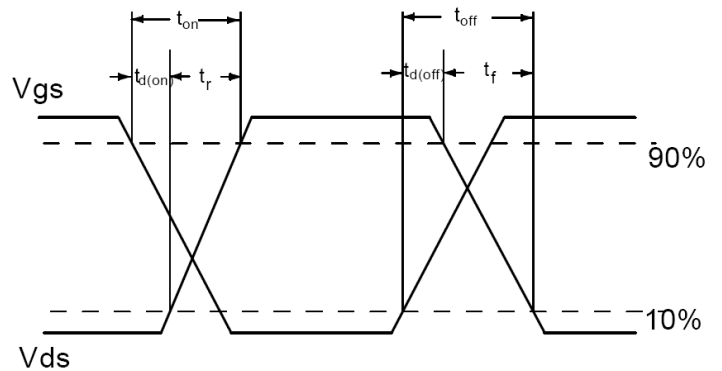
Electrical Characterizes @T_A=25°C unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
V _{(BR)DSS}	Drain-to-Source breakdown voltage	-30	—	—	V	V _{GS} = 0V, I _D = -250μA
R _{DS(on)}	Static Drain-to-Source on-resistance	—	37	52	mΩ	V _{GS} =-10V, I _D = -4.1A
		—	54	87		V _{GS} =-4.5V, I _D = -3A
V _{GS(th)}	Gate threshold voltage	-1	—	-3	V	V _{DS} = V _{GS} , I _D = -250μA
		—	-1.4	—		T _J = 125°C
I _{DSS}	Drain-to-Source leakage current	—	—	-1	μA	V _{DS} = -24V, V _{GS} = 0V
		—	—	-50		T _J = 125°C
I _{GSS}	Gate-to-Source forward leakage	—	—	100	nA	V _{GS} = 20V
		—	—	-100		V _{GS} = -20V
Q _g	Total gate charge	—	17	—	nC	I _D = -6A, V _{DS} = -25V, V _{GS} = -10V
Q _{gs}	Gate-to-Source charge	—	2.5	—		
Q _{gd}	Gate-to-Drain("Miller") charge	—	5.0	—		
t _{d(on)}	Turn-on delay time	—	7.2	—	ns	V _{GS} =-10V, V _{DS} = -25V, R _{GEN} =3Ω,
t _r	Rise time	—	4.8	—		
t _{d(off)}	Turn-Off delay time	—	24	—		
t _f	Fall time	—	11	—		
C _{iss}	Input capacitance	—	665	—	pF	V _{GS} = 0V, V _{DS} = -15V, f = 1MHz
C _{oss}	Output capacitance	—	108	—		
C _{rss}	Reverse transfer capacitance	—	83	—		

Source-Drain Ratings and Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
I _S	Continuous Source Current (Body Diode)	—	—	-4.1 ①	A	MOSFET symbol showing the integral reverse p-n junction diode.
I _{SM}	Pulsed Source Current (Body Diode)	—	—	-20	A	
V _{SD}	Diode Forward Voltage	—	-0.79	-1.0	V	I _S =1A, V _{GS} =0V
t _{rr}	Reverse Recovery Time	—	9.7	—	ns	T _J = 25°C, I _F = -6A, di/dt = 100A/μs
Q _{rr}	Reverse Recovery Charge	—	3.8	—	nC	

Test circuits and Waveforms

EAS test circuit:

Gate charge test circuit:

Switching time test circuit:

Switch Waveforms:


Notes:

- ① Calculated continuous current based on maximum allowable junction temperature.
- ② Repetitive rating; pulse width limited by max. junction temperature.
- ③ The power dissipation PD is based on max. junction temperature, using junction-to-case thermal resistance.
- ④ The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$

Typical electrical and thermal characteristics

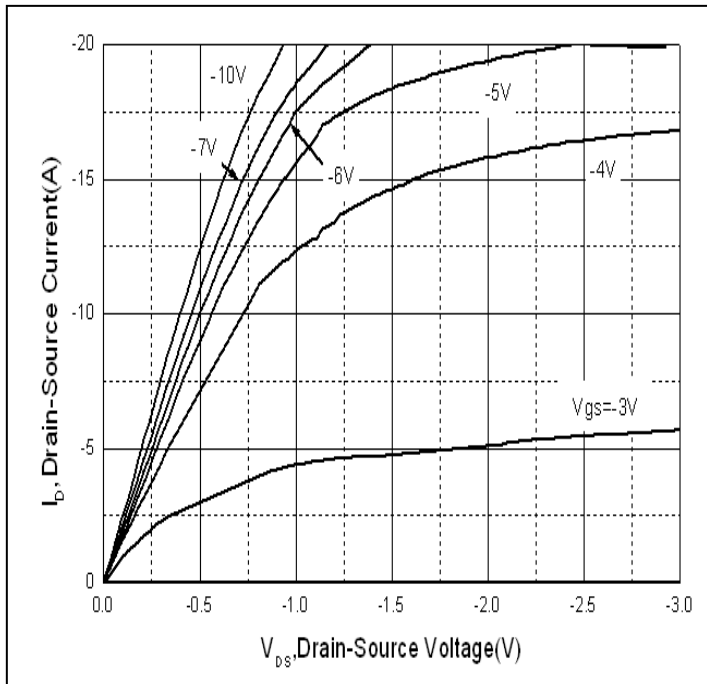


Figure 1: Typical Output Characteristics

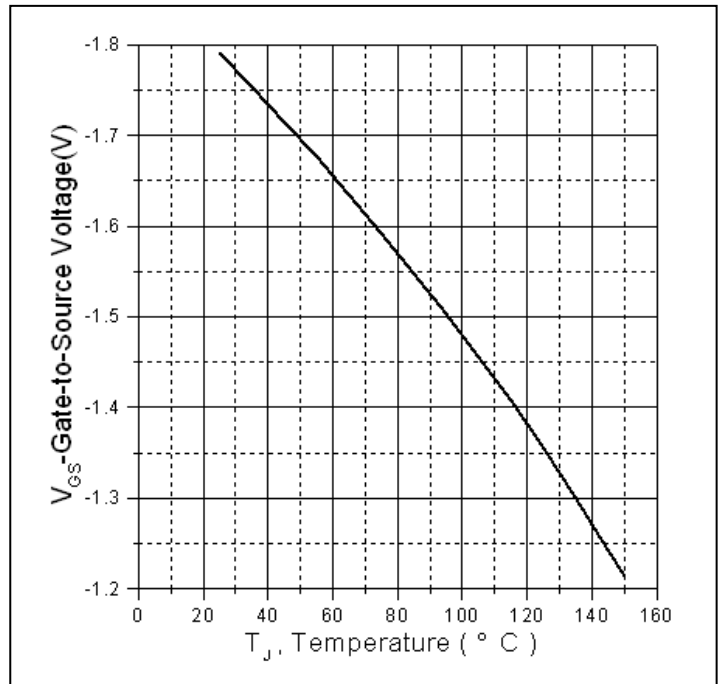


Figure 2. Gate to source cut-off voltage

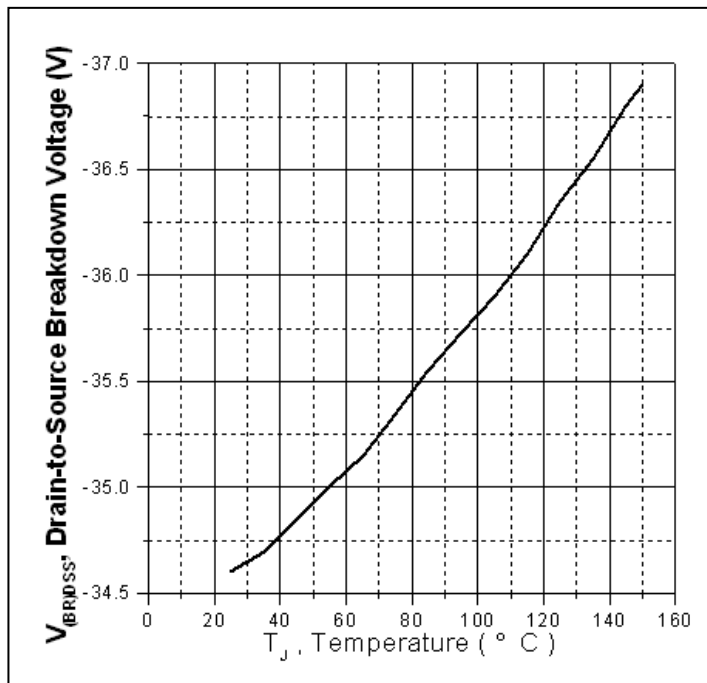


Figure 3. Drain-to-Source Breakdown Voltage Vs. Case Temperature

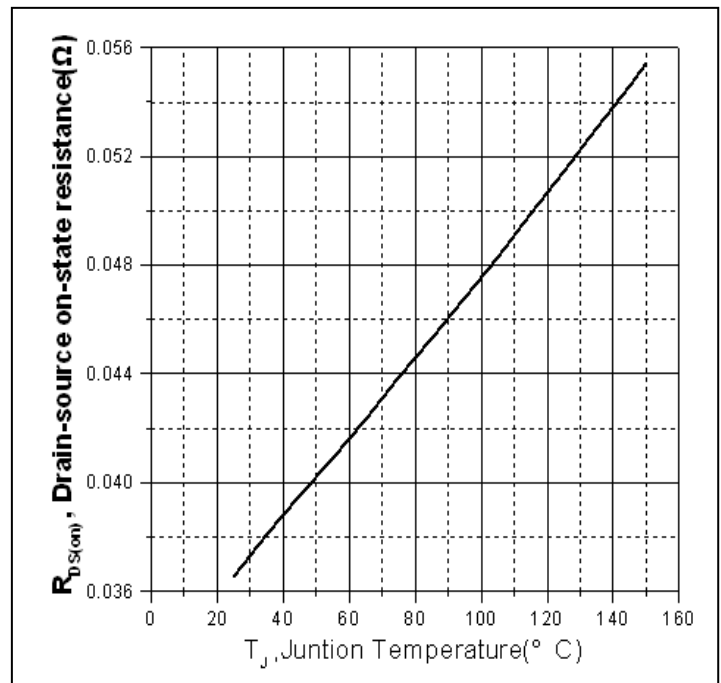


Figure 4: Normalized On-Resistance Vs. Case Temperature

Typical electrical and thermal characteristics

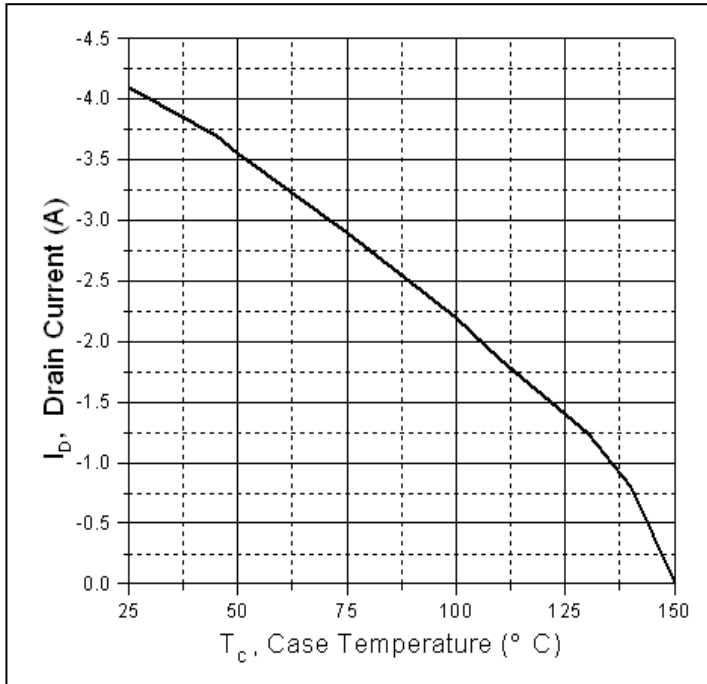


Figure 5. Maximum Drain Current Vs. Case Temperature

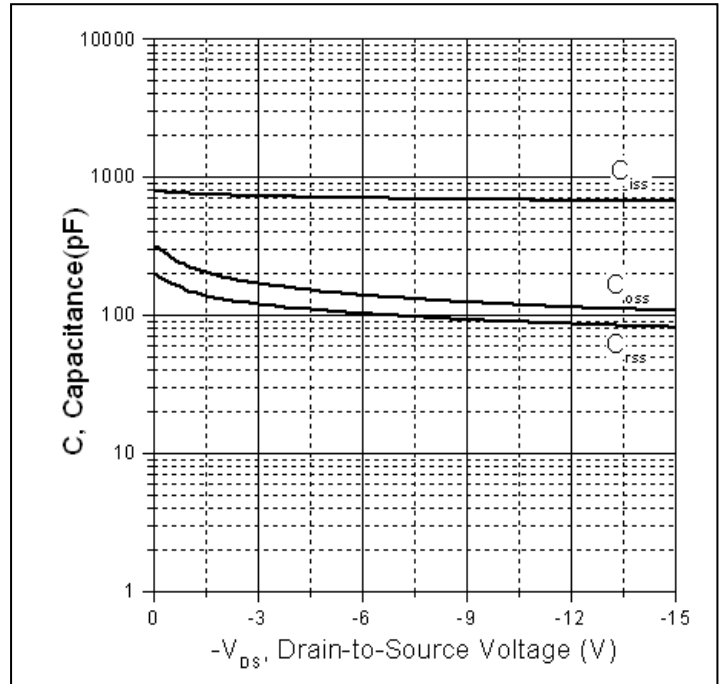


Figure 6. Typical Capacitance Vs. Drain-to-Source Voltage

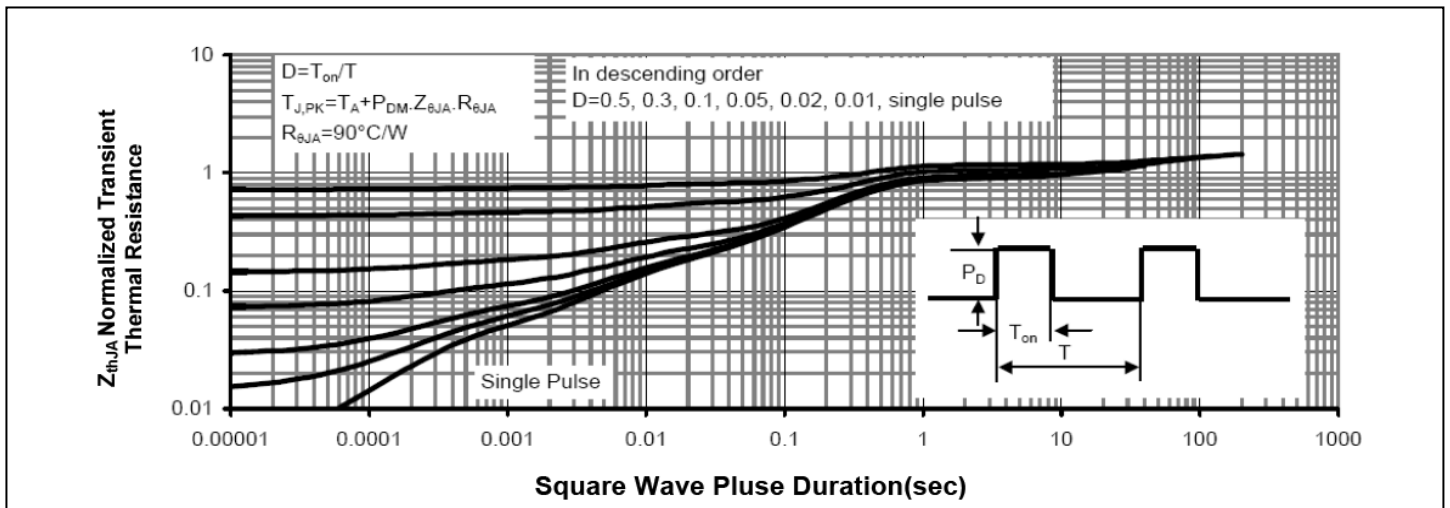
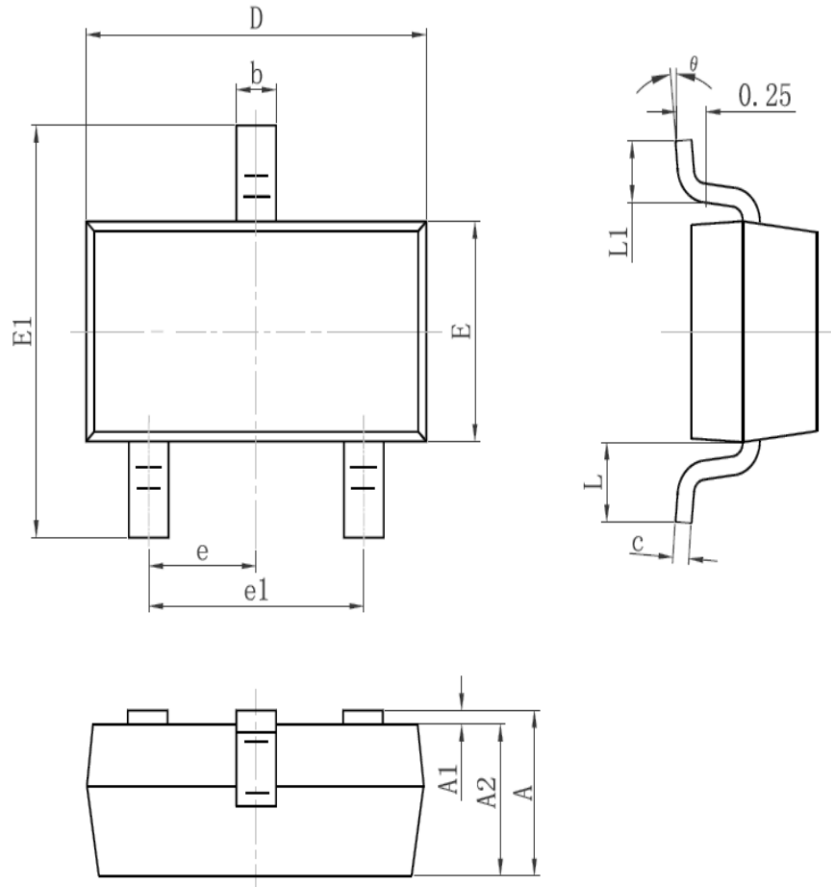


Figure7. Maximum Effective Transient Thermal Impedance Junction-to-Case

Mechanical Data:

SOT-23 PACKAGE OUTLINE DIMENSION



Symbol	Dimension In Millimeters		Dimension In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.95TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.55REF		0.022REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

Ordering and Marking Information**Device Marking: 3339**

Package (Available)
SOT-23
Operating Temperature Range
C : -55 to 150 °C

Devices per Unit

Package Type	Units/Tape	Tapes/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
SOT23	3000	10	30000	4	120000

Reliability Test Program

Test Item	Conditions	Duration	Sample Size
High Temperature Reverse Bias(HTRB)	T _j =125°C to 150°C @ 80% of Max V _{DSS} /V _{CES} /V _R	168 hours 500 hours 1000 hours	3 lots x 77 devices
High Temperature Gate Bias(HTGB)	T _j =150°C @ 100% of Max V _{GSS}	168 hours 500 hours 1000 hours	3 lots x 77 devices

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